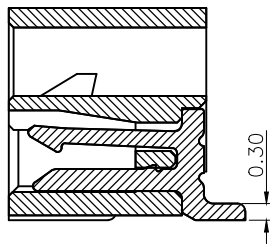
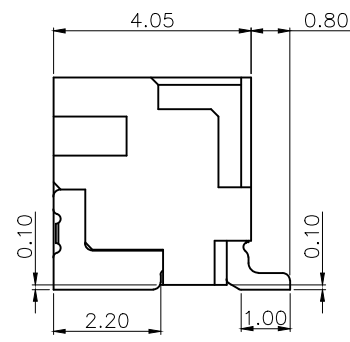
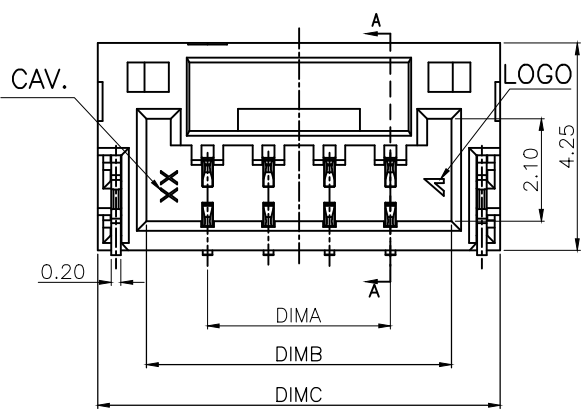


RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05



SECTION A-A

NOTES:

1. MATERIAL:
 - 1.1 HOUSING: THERMOPLASTIC, HIGH TEMP.,UL94V-0.
 - 1.2 CONTACT: PHOSPHOR BRONZE.
 - 1.3 FITTING NAIL: BRASS
2. FINISH:
 - 2.1 TERMINAL:
 - 50u" MIN NICKEL UNDERPLATING OVERALL.
 - N:80u" MIN MATT TIN PLATING OVERALL.
 - 2:GOLD FLASH ON CONTACT AND SOLDER AREA
 - A:3U" GOLD ON CONTACT AND GOLD FLASH ON SOLDER AREA
 - 2.2 FITTING NAIL:
 - 50u" MIN NICKEL UNDERPLATING OVERALL.
 - N:80u" MIN MATT TIN PLATING OVERALL.
3. REFLOW SOLDER CAPABLE TO 260°C
PER ACES SPEC.
4. SPEC.PLS REFER TO PS-51451-XXXX-XXX
5. PACKAGE PLS REFER TO 51451-XXXX-U-TRP
6. PART NUMBER :

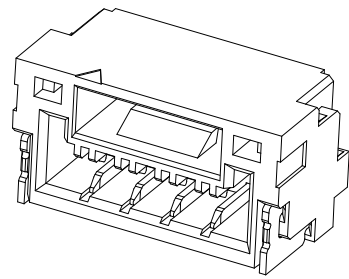
51451-XXX X X-XXX

NO OF CKTS
PACKING
0:TAPE & REEL

XXX	MATERIAL	COLOR OF HOUSING
001	LCP	NATURAL
002	LCP	BLACK

PLATING
N:MATT TIN
2:GOLD FLASH
A:3U" GOLD ON CONTACT

CKT	A	B	C
002	1.25	3.75	5.75
003	2.50	5.00	7.00
004	3.75	6.25	8.25
005	5.00	7.50	9.50
006	6.25	8.75	10.75
007	7.50	10.00	12.00
008	8.75	11.25	13.25
009	10.00	12.50	14.50
010	11.25	13.75	15.75
011	12.50	15.00	17.00
012	13.75	16.25	18.25
013	15.00	17.50	19.50
014	16.25	18.75	20.75
015	17.50	20.00	22.00



QUALITY SYMBOLS MAJOR Ⓢ CRITICAL Ⓢ	DRAWN BY YANJINXIU DATE 22/12/16	
	CHECKED BY XuZhiYong DATE 22/12/16	
GENERAL TOLERANCES (UNLESS SPECIFIED) X. ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	APPROVED BY XuZhiYong DATE 22/12/16	TITLE 1.25mm Pitch WTB Wafer Conn. SMT R/A S/R Type.
	UNITS mm	SCALE 1:1
	SHEET NO. 1 OF 1	REV F
		DWG NO. 51451-XXXX-XXX